Amendments to the Abstract:

~~An object of the present invention is to provide a~~ A technology is provided that can seal the opening ~~of the interposer by~~ in a wiring board using a transfer mold ~~with the leak of the~~ insulating resin from the ~~above-described~~ opening ~~prevented~~. A mold die ~~comprising~~ is used which includes a first die having a recess in a predetermined form and a second flat die~~, the above-described mold die being for disposing the above-described~~. The first die is disposed on a surface of a wiring board which has a plurality of openings and ~~bears~~ on which a semiconductor chip is mounted via an elastic material~~, which surface bears the above-described semiconductor chip, and for disposing the above-described~~. The second die is disposed on a back surface of the ~~above-described surface of the above-described~~ wiring board opposite the surface on which ~~bears~~ the ~~above-described~~ semiconductor chip is mounted. The mold is used~~, and~~ for sealing with an insulating resin ~~a~~ the periphery of the ~~above-described~~ semiconductor chip and at least one of the ~~above-described~~ openings of the ~~above-described~~ wiring board, wherein the above-described second die ~~comprises~~ has a protrusion around an area overlapping the ~~above-described~~ opening to be sealed with the ~~above-described~~ insulating resin.

~~(Selected Figure) Fig. 3~~